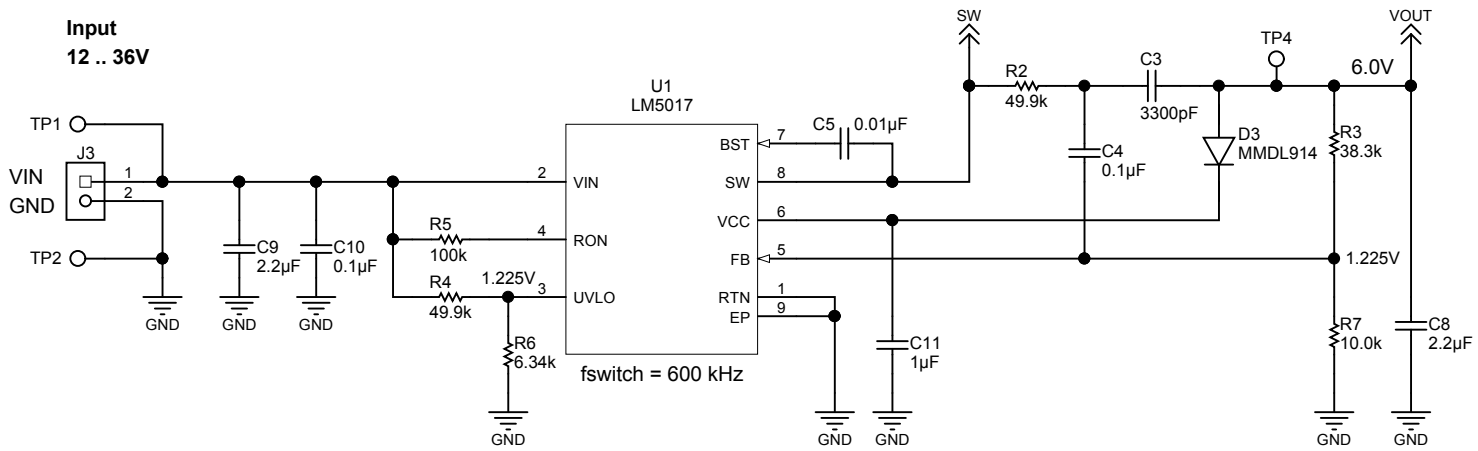
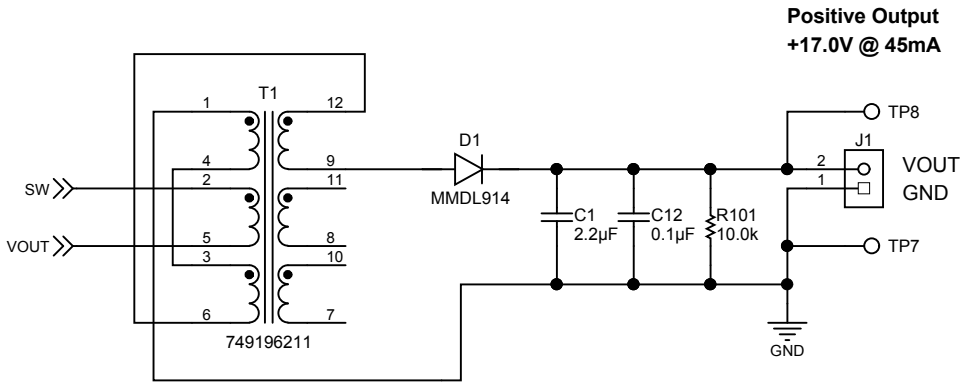
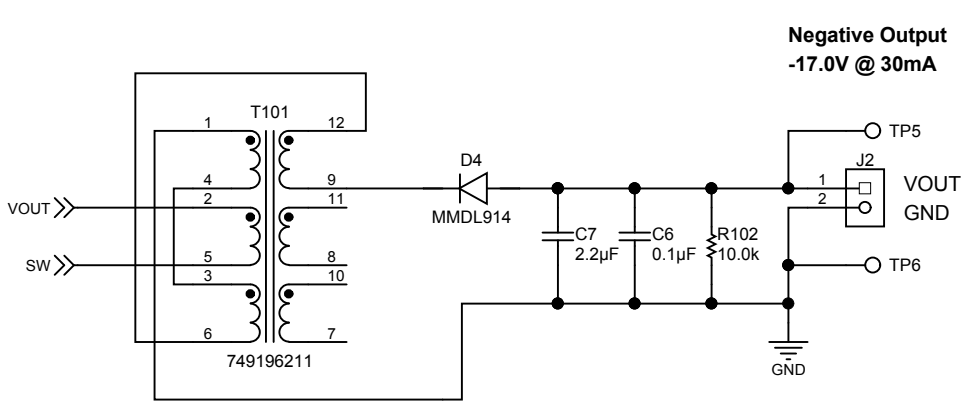
Revision History	
Revision	Notes
A	* Built & tested



Transformer

* Npri : Nsec = 1 : 3 = 21.6 uH : 194.4 uH
* Positive Output (Measured Values)
  - Primary: 320mA peak / 170mA rms
  - Secondary: 110mA peak / 65mA rms
* Negative Output (Measured Values)
  - Primary: 290mA peak / 125mA rms
  - Secondary: 80mA peak / 50mA rms





Design Notes

* Parts with RefDes > 100 have no footprint on PCB
* Modified TIDA-00129 Board

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Number: PMP10101	Rev: A	Designed for: Public Release	Mod. Date: 9/22/2014
		Project Title: Dual Output Industrial Fly-Buck	
		Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: Variant name not interpreted	Sheet: 1 of 1
Drawn By:		File: PMP10101RevA.SchDoc	Size: A4
Engineer: Matthias Ulmann		Contact: http://www.ti.com/support	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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